

74VCXH16244

Low Voltage 16-Bit Buffer/Line Driver with Bushold

General Description

The VCXH16244 contains sixteen non-inverting buffers with 3-STATE outputs to be employed as a memory and address driver, clock driver, or bus oriented transmitter/receiver. The device is nibble (4-bit) controlled. Each nibble has separate 3-STATE control inputs which can be shorted together for full 16-bit operation.

The VCXH16244 data inputs include active bushold circuitry, eliminating the need for external pull-up resistors to hold unused or floating data inputs at a valid logic level.

The 74VCXH16244 is designed for low voltage (1.2V to 3.6V) V_{CC} applications with output capability up to 3.6V.

The 74VCXH16244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining low CMOS power dissipation.

Features

- 1.2V to 3.6V V_{CC} supply operation
- 3.6V tolerant control inputs and outputs
- Bushold on data inputs eliminating the need for external pull-up/pull-down resistors
- t_{PD}
2.5 ns max for 3.0V to 3.6V V_{CC}
- Static Drive (I_{OH}/I_{OL})
±24 mA @ 3.0V V_{CC}
- Uses patented noise/EMI reduction circuitry
- Latch-up performance exceeds 300 mA
- ESD performance:
Human body model > 2000V
Machine model > 200V
- Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA) (Preliminary)

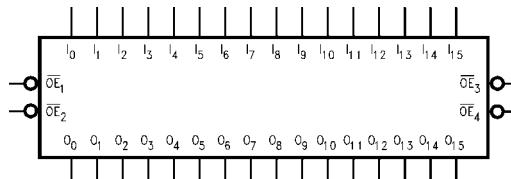
Ordering Code:

Order Number	Package Number	Package Description
74VCXH16244G (Note 1)(Note 2)	BGA54A (Preliminary)	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74VCXH16244MTD (Note 2)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 1: Ordering Code "G" indicates Tray.

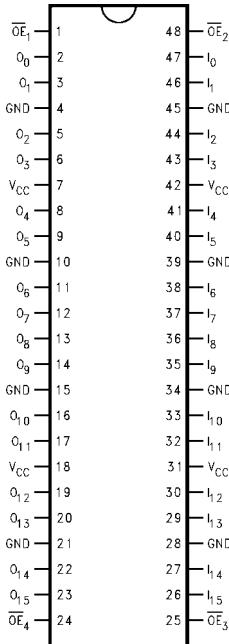
Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol

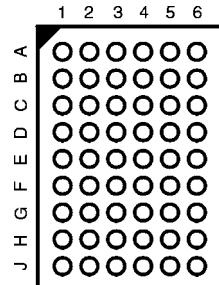


Connection Diagrams

Pin Assignment for TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

Pin Names	Description
OE _n	Output Enable Input (Active LOW)
I ₀ -I ₁₅	Bushold Inputs
O ₀ -O ₁₅	Outputs
NC	No Connect

FBGA Pin Assignments

	1	2	3	4	5	6
A	O ₀	NC	OE ₁	OE ₂	NC	I ₀
B	O ₂	O ₁	NC	NC	I ₁	I ₂
C	O ₄	O ₃	V _{CC}	V _{CC}	I ₃	I ₄
D	O ₆	O ₅	GND	GND	I ₅	I ₆
E	O ₈	O ₇	GND	GND	I ₇	I ₈
F	O ₁₀	O ₉	GND	GND	I ₉	I ₁₀
G	O ₁₂	O ₁₁	V _{CC}	V _{CC}	I ₁₁	I ₁₂
H	O ₁₄	O ₁₃	NC	NC	I ₁₃	I ₁₄
J	O ₁₅	NC	OE ₄	OE ₃	NC	I ₁₅

Truth Tables

Inputs		Outputs
OE ₁	I ₀ -I ₃	O ₀ -O ₃
L	L	L
L	H	H
H	X	Z
Inputs		Outputs
OE ₂	I ₄ -I ₇	O ₄ -O ₇
L	L	L
L	H	H
H	X	Z
Inputs		Outputs
OE ₃	I ₈ -I ₁₁	O ₈ -O ₁₁
L	L	L
L	H	H
H	X	Z
Inputs		Outputs
OE ₄	I ₁₂ -I ₁₅	O ₁₂ -O ₁₅
L	L	L
L	H	H
H	X	Z

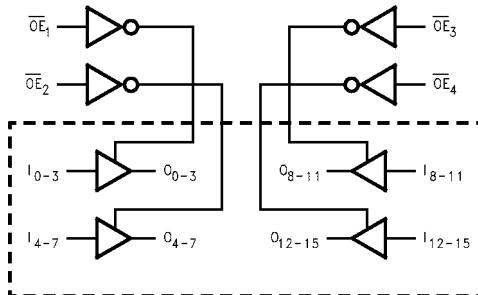
H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial (HIGH or LOW, inputs may not float)
Z = High Impedance

Functional Description

The 74VCXH16244 contains sixteen non-inverting buffers with 3-STATE outputs. The device is nibble (4 bits) controlled with each nibble functioning identically, but independent of each other. The control pins may be shorted together to obtain full 16-bit operation. The 3-STATE out-

puts are controlled by an Output Enable (\overline{OE}_n) input. When \overline{OE}_n is LOW, the outputs are in the 2-state mode. When \overline{OE}_n is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the inputs.

Logic Diagram



74VCXH16244

Absolute Maximum Ratings ^(Note 3)		Recommended Operating Conditions ^(Note 5)				
Supply Voltage (V_{CC})	-0.5V to +4.6V	Power Supply				
DC Input Voltage (V_I)	-0.5V to +4.6V	Operating	1.2V to 3.6V			
Output Voltage (V_O)		Input Voltage	-0.3V to +3.6V			
Outputs 3-STATED	-0.5V to +4.6V	Output Voltage (V_O)				
Outputs Active (Note 4)	-0.5V to $V_{CC} + 0.5V$	Output in Active States	0.0V to V_{CC}			
DC Input Diode Current (I_{IK}) $V_I < 0V$	-50 mA	Output in 3-STATE	0.0V to 3.6V			
DC Output Diode Current (I_{OK})		Output Current in I_{OH}/I_{OL}				
$V_O < 0V$	-50 mA	$V_{CC} = 3.0V$ to 3.6V	± 24 mA			
$V_O > V_{CC}$	+50 mA	$V_{CC} = 2.3V$ to 2.7V	± 18 mA			
DC Output Source/Sink Current (I_{OH}/I_{OL})	± 50 mA	$V_{CC} = 1.65V$ to 2.3V	± 6 mA			
DC V_{CC} or GND Current per Supply Pin (I_{CC} or GND)	± 100 mA	$V_{CC} = 1.4V$ to 1.6V	± 2 mA			
Storage Temperature Range (T_{STG})	-65°C to +150°C	$V_{CC} = 1.2V$	± 100 μ A			
		Free Air Operating Temperature (T_A)	-40°C to +85°C			
		Minimum Input Edge Rate ($\Delta t/\Delta V$)				
		$V_{IN} = 0.8V$ to 2.0V, $V_{CC} = 3.0V$	10 ns/V			
Note 3: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.						
Note 4: I_O Absolute Maximum Rating must be observed.						
Note 5: Floating or unused control inputs must be held HIGH or LOW.						
DC Electrical Characteristics						
Symbol	Parameter	Conditions	V_{CC} (V)	Min	Max	
V_{IH}	HIGH Level Input Voltage		2.7 - 3.6 2.3 - 2.7 1.65 - 2.3 1.4 - 1.6 1.2	2.0 1.6 $0.65 \times V_{CC}$ $0.65 \times V_{CC}$ $0.65 \times V_{CC}$		V
V_{IL}	LOW Level Input Voltage		2.7 - 3.6 2.3 - 2.7 1.65 - 2.3 1.4 - 1.6 1.2		0.8 0.7 $0.35 \times V_{CC}$ $0.35 \times V_{CC}$ $0.05 \times V_{CC}$	V
V_{OH}	HIGH Level Output Voltage	$I_{OH} = -100 \mu A$	2.7 - 3.6	$V_{CC} - 0.2$		V
		$I_{OH} = -12 mA$	2.7	2.2		
		$I_{OH} = -18 mA$	3.0	2.4		
		$I_{OH} = -24 mA$	3.0	2.2		
		$I_{OH} = -100 \mu A$	2.3 - 2.7	$V_{CC} - 0.2$		
		$I_{OH} = -6 mA$	2.3	2.0		
		$I_{OH} = -12 mA$	2.3	1.8		
		$I_{OH} = -18 mA$	2.3	1.7		

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC} (V)	Min	Max	Units
V _{OL}	LOW Level Output Voltage	I _{OL} = 100 µA	2.7 - 3.6		0.2	
		I _{OL} = 12 mA	2.7		0.4	
		I _{OL} = 18 mA	3.0		0.4	
		I _{OL} = 24 mA	3.0		0.55	
		I _{OL} = 100 µA	2.3 - 2.7		0.2	
		I _{OL} = 12 mA	2.3		0.4	
		I _{OL} = 18 mA	2.3		0.6	
		I _{OL} = 100 µA	1.65 - 2.3		0.2	
		I _{OL} = 6 mA	1.65		0.3	
		I _{OL} = 100 µA	1.4 - 1.6		0.2	
I _I	Input Leakage Current	I _I = 100 µA	1.4		0.35	
		I _I = 100 µA	1.2		0.05	
I _{I(HOLD)}	Bushold Input Minimum Drive Hold Current	V _I = V _{CC} or GND	1.2 - 3.6		±5.0	µA
		V _I = 0.8V	3.0	75.0		
		V _I = 2.0V	3.0	-75.0		
		V _I = 0.7V	2.3	45.0		
		V _I = 1.6V	2.3	-45.0		
		V _I = 0.57V	1.65	25.0		
I _{I(OD)}	Bushold Input Over-Drive Current to Change State	V _I = 1.07V	1.65	-25.0		
		(Note 6)	3.6	450		
		(Note 7)	3.6	-450		
		(Note 6)	2.7	300		
		(Note 7)	2.7	-300		
		(Note 6)	1.95	200		
I _{OZ}	3-STATE Output Leakage	(Note 7)	1.95	-200		
		V _O = V _{IH} or V _{IL}	2.7 - 3.6		±10.0	µA
I _{OFF}	Power-OFF Leakage Current	0 ≤ (V _O) ≤ 3.6V	0		10.0	µA
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	1.2 - 3.6		20.0	µA
		V _{CC} ≤ (V _O) ≤ 3.6V (Note 8)	1.2 - 3.6		±20.0	µA
ΔI _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} - 0.6V	2.7 - 3.6		750	µA

Note 6: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 7: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

Note 8: Outputs disabled or 3-STATE only.

AC Electrical Characteristics (Note 9)

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C		Units	Figure Number
				Min	Max		
t _{PHL} t _{PLH}	Propagation Delay	C _L = 30 pF, R _L = 500Ω	3.3 ± 0.3	0.8	2.5	ns	Figures 1, 2
			2.5 ± 0.2	1.0	3.0		
			1.8 ± 0.15	1.5	6.0		Figures 5, 6
		C _L = 15 pF, R _L = 2 kΩ	1.5 ± 0.1	1.0	12.0		
			1.2	1.5	30.0		
t _{PZL} t _{PZH}	Output Enable Time	C _L = 30 pF, R _L = 500Ω	3.3 ± 0.3	0.8	3.5	ns	Figures 1, 3, 4
			2.5 ± 0.2	1.0	4.1		
			1.8 ± 0.15	1.5	8.2		Figures 5, 7, 8
		C _L = 15 pF, R _L = 2 kΩ	1.5 ± 0.1	1.0	16.4		
			1.2	1.5	41.0		
t _{PLZ} t _{PHZ}	Output Disable Time	C _L = 30 pF, R _L = 500Ω	3.3 ± 0.3	0.8	3.5	ns	Figures 1, 3, 4
			2.5 ± 0.2	1.0	3.8		
			1.8 ± 0.15	1.5	6.8		Figures 5, 7, 8
		C _L = 15 pF, R _L = 2 kΩ	1.5 ± 0.1	1.0	13.6		
			1.2	1.5	34.0		
t _{OSHL} t _{OSLH}	Output to Output Skew (Note 10)	C _L = 30 pF, R _L = 500Ω	3.3 ± 0.3		0.5	ns	
			2.5 ± 0.2		0.5		
			1.8 ± 0.15		0.75		
		C _L = 15 pF, R _L = 2 kΩ	1.5 ± 0.1		1.5		
			1.2		1.5		

Note 9: For C_L = 50 pF, add approximately 300 ps to the AC maximum specification.

Note 10: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

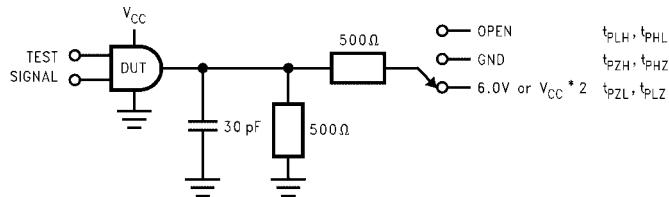
Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = +25°C		Units
				Typical		
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	C _L = 30 pF, V _{IH} = V _{CC} , V _{IL} = 0V	1.8	0.25	V	
			2.5	0.6		
			3.3	0.8		
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	C _L = 30 pF, V _{IH} = V _{CC} , V _{IL} = 0V	1.8	-0.25	V	
			2.5	-0.6		
			3.3	-0.8		
V _{OHV}	Quiet Output Dynamic Valley V _{OH}	C _L = 30 pF, V _{IH} = V _{CC} , V _{IL} = 0V	1.8	1.5	V	
			2.5	1.9		
			3.3	2.2		

Capacitance

Symbol	Parameter	Conditions	T _A = +25°C		Units
			Typical		
C _{IN}	Input Capacitance	V _{CC} = 1.8, 2.5V or 3.3V, V _I = 0V or V _{CC}	6.0		pF
C _{OUT}	Output Capacitance	V _I = 0V or V _{CC} , V _{CC} = 1.8V, 2.5V or 3.3V	7.0		pF
C _{PD}	Power Dissipation Capacitance	V _I = 0V or V _{CC} , f = 10 MHz, V _{CC} = 1.8V, 2.5V or 3.3V	20.0		pF

AC Loading and Waveforms (V_{CC} $3.3V \pm 0.3V$ to $1.8V \pm 0.15V$)



TEST	SWITCH
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	$6V$ at $V_{CC} = 3.3 \pm 0.3V$; $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V, 1.8V \pm 0.15V$
t_{PZH}, t_{PHZ}	GND

FIGURE 1. AC Test Circuit

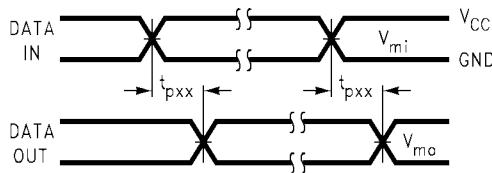


FIGURE 2. Waveform for Inverting and Non-Inverting Functions

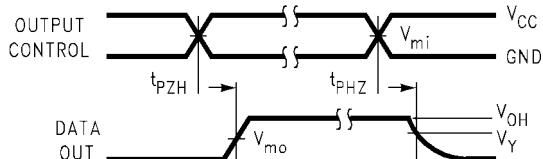


FIGURE 3. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

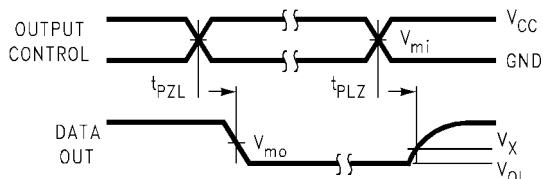
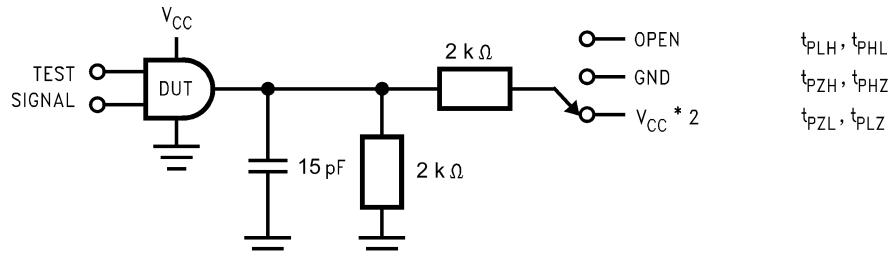


FIGURE 4. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

Symbol	V_{CC}		
	$3.3V \pm 0.3V$	$2.5V \pm 0.2V$	$1.8V \pm 0.15V$
V_{mi}	$1.5V$	$V_{CC}/2$	$V_{CC}/2$
V_{mo}	$1.5V$	$V_{CC}/2$	$V_{CC}/2$
V_X	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$	$V_{OL} + 0.15V$
V_Y	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$	$V_{OH} - 0.15V$

AC Loading and Waveforms (V_{CC} $1.5 \pm 0.1V$ to $1.2V$)

TEST	SWITCH
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	$V_{CC} \times 2$ at $V_{CC} = 1.5 \pm 0.1V$
t_{PZH}, t_{PHZ}	GND

FIGURE 5. AC Test Circuit

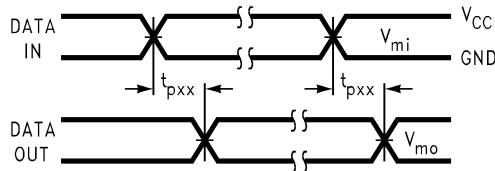


FIGURE 6. Waveform for Inverting and Non-Inverting Functions

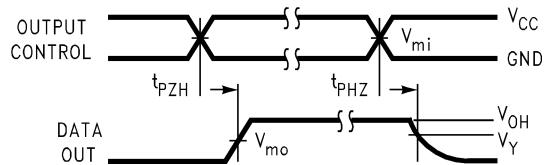


FIGURE 7. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

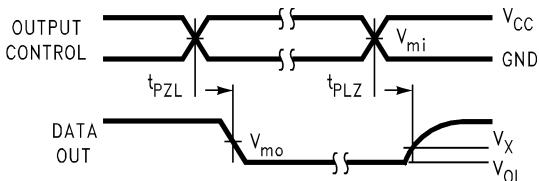
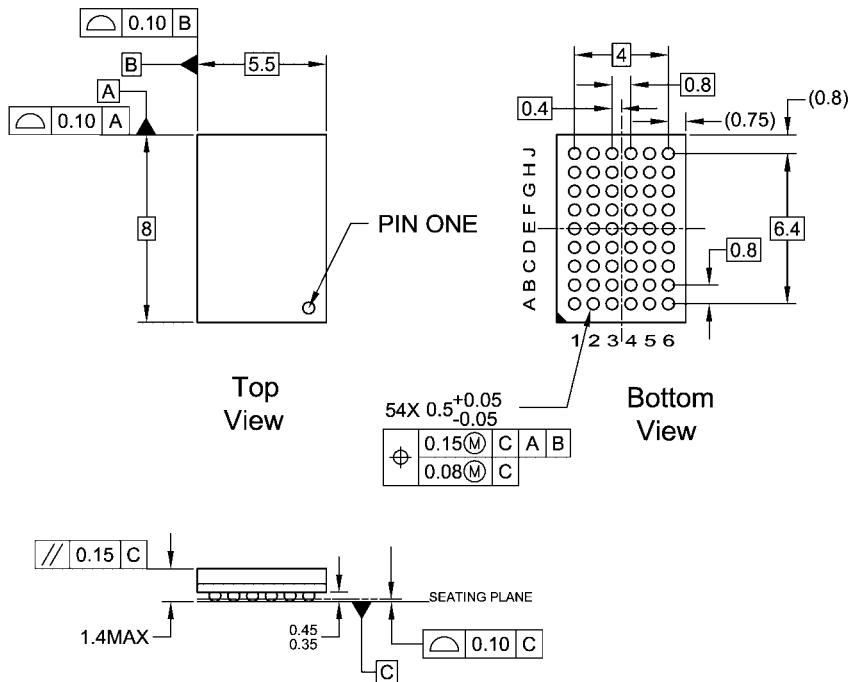


FIGURE 8. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

Symbol	V_{CC}
	$1.5V \pm 0.1V$
V_{mi}	$V_{CC}/2$
V_{mo}	$V_{CC}/2$
V_X	$V_{OL} + 0.1V$
V_Y	$V_{OH} - 0.1V$

Physical Dimensions inches (millimeters) unless otherwise noted



NOTES:

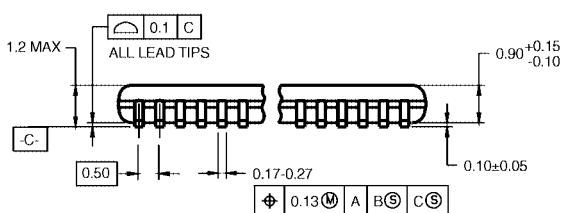
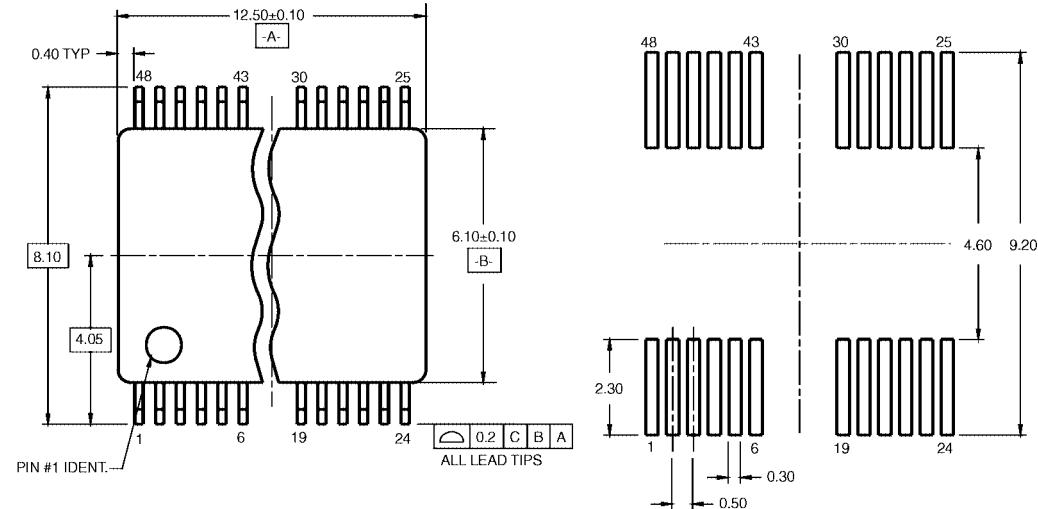
- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
.35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
- D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54RevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC M0-205, 5.5mm Wide
Package Number BGA54A
Preliminary

74VCXH16244 Low Voltage 16-Bit Buffer/Line Driver with Bushold

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

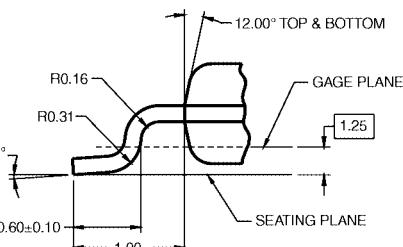


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTD48RevB1



DETAIL A

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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